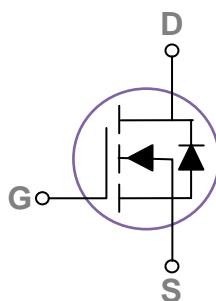
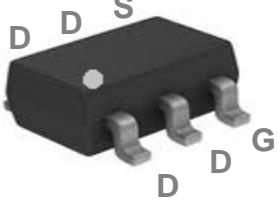


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-6 Pin Configuration



BVDSS	RDS(ON)	ID
40V	35mΩ	5A

Features

- 40V, 5A, RDS(ON) = 35mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	5	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	3	A
I_{DM}	Drain Current – Pulsed ¹	20	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	1.56	W
	Power Dissipation – Derate above 25°C	0.012	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=3\text{A}$	---	28	35	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=2\text{A}$	---	38	45	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=3\text{A}$	---	6.5	---	S

Dynamic and switching Characteristics

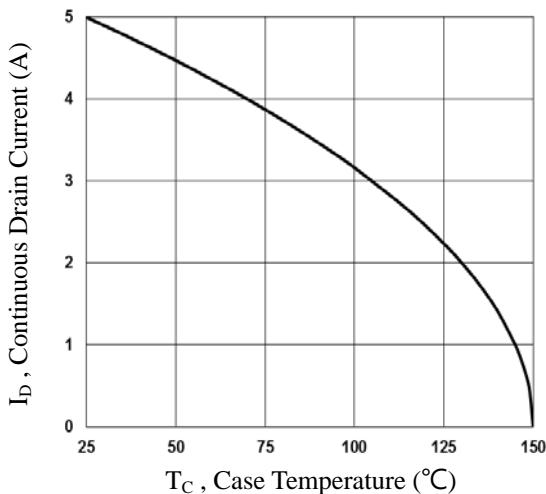
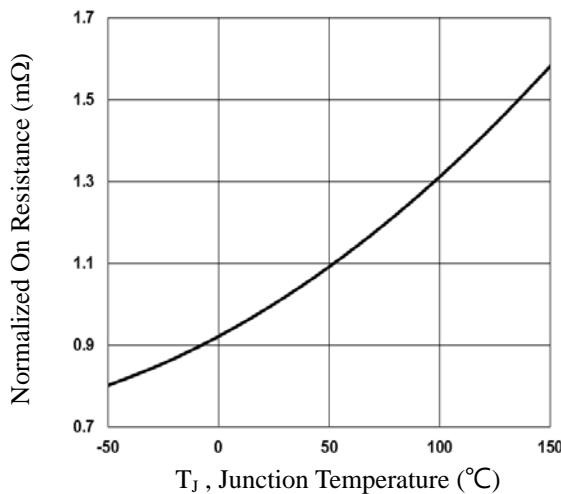
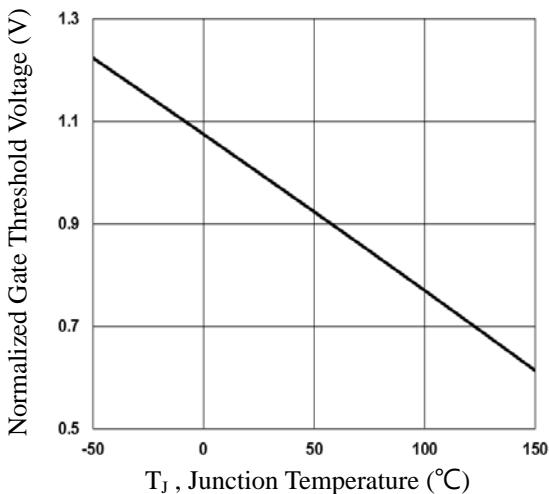
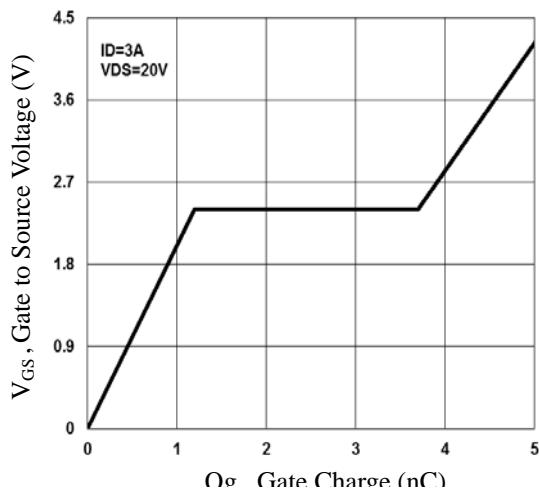
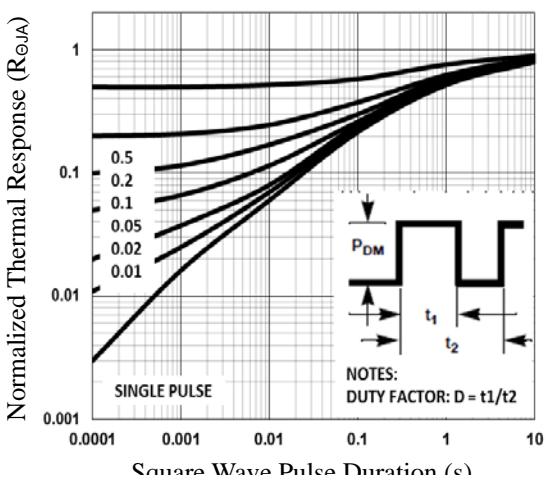
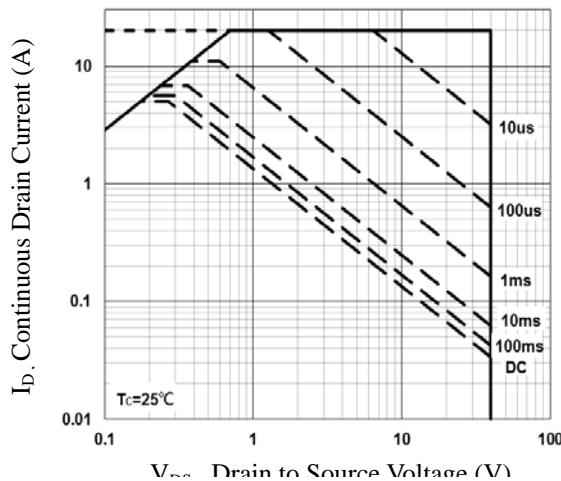
Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=3\text{A}$	---	5.2	10	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.2	2.4	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	2.5	5	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=25\Omega$ $I_D=1\text{A}$	---	3.2	6	ns
T_r	Rise Time ^{2,3}		---	8.6	16	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	18	36	
T_f	Fall Time ^{2,3}		---	6	12	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	420	800	pF
C_{oss}	Output Capacitance		---	65	120	
C_{rss}	Reverse Transfer Capacitance		---	40	80	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	5	A
I_{SM}	Pulsed Source Current ²		---	---	10	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time		---	---	---	ns
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	---	---	nC

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized $R_{DS(on)}$ vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

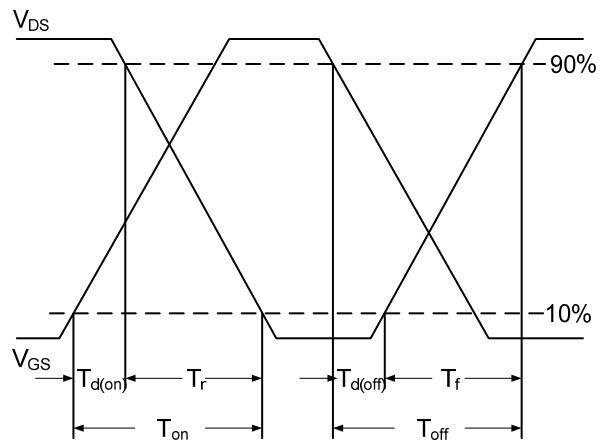


Fig.7 Switching Time Waveform

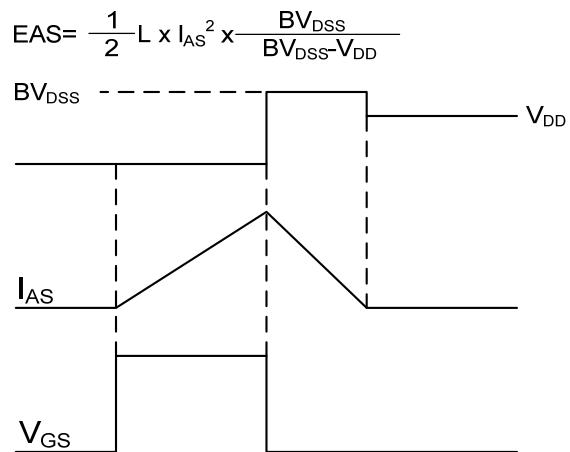
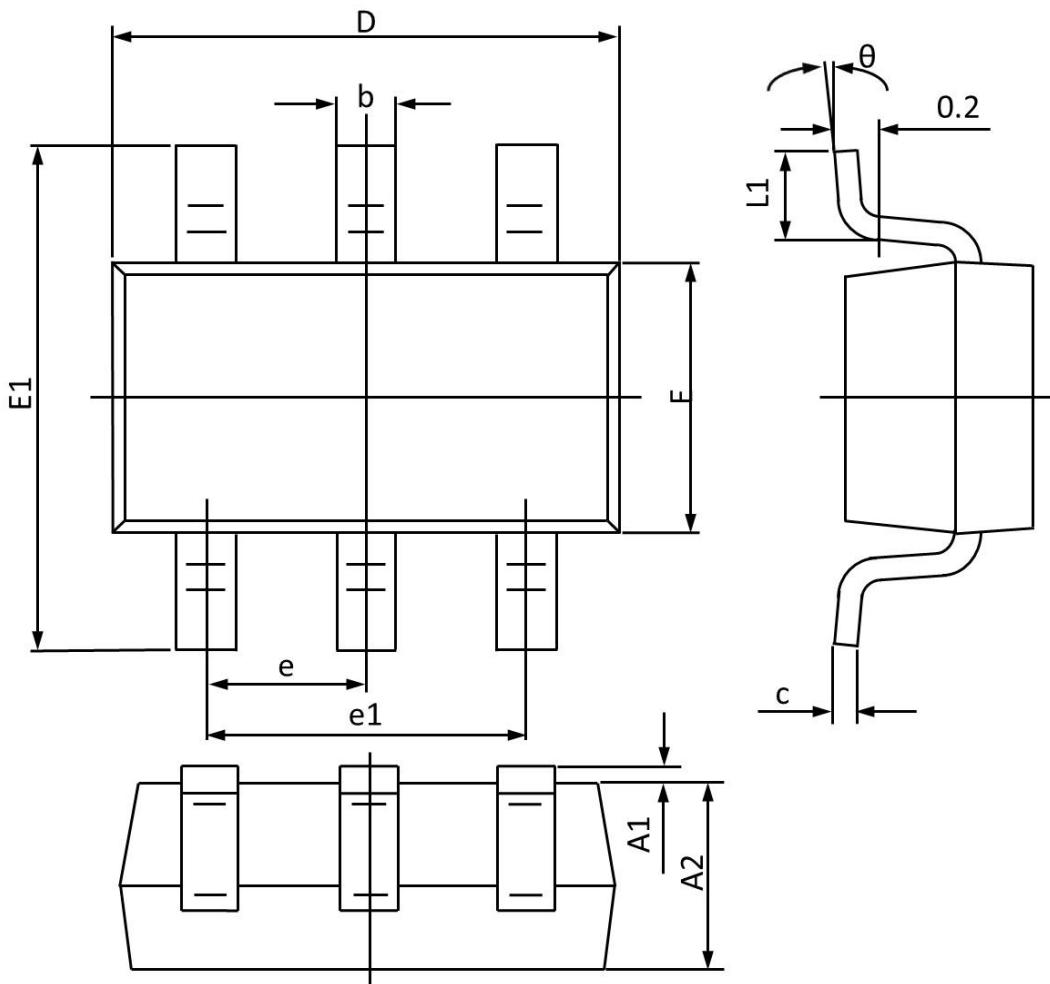


Fig.8 EAS Waveform

SOT23-6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°